

## ABSTRACT OF THE DISCLOSURE

A process of forming a flexible circuit board for ink jetting is provided. The process includes the steps of: providing an insulation tape; forming conductive traces on the insulation tape; and forming a photo-polymer layer filling between the  
5 conductive traces, wherein parts of the conductive traces are exposed to form a plurality of contacts. The material of the insulation tape can be polyimide, Teflon, polyamide, polymethylmethacrylate, polycarbonate, polyester, polyamide polyethylene-terephthalate copolymer, or any combination of the above materials. The material of the photo-polymer layer can be solder mask or polyimide.

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